

Quarterly Reliability Monitoring Results

Quarters: Q1/2022 to Q4/2023

Based on structural similarity

Supplier Nexperia B.V. Name of Laboratory Assembly reliability labs Based on AEC-Q101 Test		User Part Number BAT54CW-Q Part Description										
								Nexperia DHAM Schottky				
								SMD package				
		Test Conditions	Duration	# Lots	# Quantity	# Rejects						
			TEST									
			Pre- and Post-Stress									
# E1	Electrical Test	Tamb = 25 °C	N/A	see below	all parts	see below						
		JESD22-A113										
		Bake Tamb = 125 °C	24 hours									
	PC	Soak Tamb = 85 °C, RH = 85%	168 hours									
# A1	Preconditioning	Reflow soldering	3 cycles	1514	64430	0						
		MIL-STD-750-1										
	HTRB	M1038 Method A										
	High Temperature Reverse											
# B1	Bias	reverse voltage ^[1]	1000 hours	206	9320	0						
	TC	JESD22-A104										
# A4	Temperature Cycling	-65 °C to Tjmax, not to exceed 150°C	1000 cycles	311	14080	0						
	UHAST	JESD22-A118										
# A2 a=	Unbiased HAST	Tamb = 130 °C, RH = 85 %										
# A3 or	Olibiased HAST	· · · · · · · · · · · · · · · · · · ·	—96 hours	311	14080	0						
		JESD22-A102										
" * 2 L	AC Autoclave	Tamb = 121 °C, RH = 100 %										
# A3 alt	Autociave	Pressure = 205 kPa (29.7 psia)										
	H3TRB	JESD22-A101										
	High Humidity High	Tamb = 85 °C, RH = 85%, VR = 80 % of										
# A2 alt	Temperature Reverse Bias	rated reverse voltage ^{[1], [2]}	1000 hours	311	14080	0						
# AZ dIL	remperature neverse bias		1000 Hours	211	14000	U						
	IOL	MIL-STD-750 Method 1037 ton = toff, devices powered to insure $\Delta T_j =$										
# A5	Intermittent Operating Life		1000 hours	312	14120	0						
# A3	Intermittent Operating Life	100 C for 15000 cycles	1000 110015	312	14120	U						
	RSH	JESD22-A111										
# C8	Resistance to Solder Heat		10 s	269	8070	0						
50	SD		200	203	2370	~						
# C10	Solderability	J-STD-002		222	6660	0						
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^[1] The physical limitations of Schottky diodes have to be considered (thermal runaway).

Calculation of FIT and MTTF

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

Wafer Fab	Technology	Quantity	Rejects	Failure Rate (FIT)	MTTF (hrs)
Nexperia					
DHAM	Schottky	9320	0	0,46	2,19E+09

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^[2] The maximum applied voltage is limited by test chamber set up and does not exceed 115V.